

## STP16NE06 STP16NE06FP

# N - CHANNEL 60V - 0.08 $\Omega$ - 16A - TO-220/TO-220FP STripFETTM POWER MOSFET

### **PRELIMINARY DATA**

TYPE	V <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
STP16NE06	60 V	< 0.100 Ω	16 A
STP16NE06FP	60 V	< 0.100 Ω	11 A

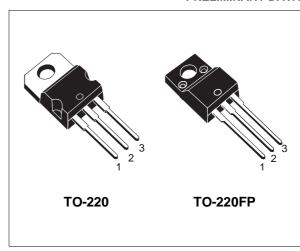
- TYPICAL  $R_{DS(on)} = 0.08 \Omega$
- AVALANCHE RUGGED TECHNOLOGY
- 100% AVALANCHE TESTED
- 175°C OPERATING TEMPERATURE
- HIGH dV/dt CAPABILITY
- APPLICATION ORIENTED CHARACTERIZATION

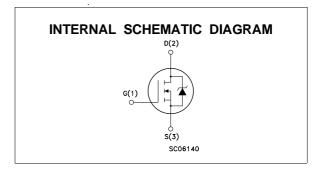
### **DESCRIPTION**

This Power Mosfet is the latest development of SGS-THOMSON unique "Single Feature Size" process whereby a single body is implanted on a strip layout structure. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalance characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

### **APPLICATIONS**

- DC MOTOR CONTROL
- DC-DC & DC-AC CONVERTERS
- SYNCHRONOUS RECTIFICATION





### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value		Unit
		STP16NE06	STP16NE06FP	
$V_{DS}$	Drain-source Voltage (V <sub>GS</sub> = 0)	6	0	V
$V_{DGR}$	Drain- gate Voltage ( $R_{GS} = 20 \text{ k}\Omega$ )	6	00	V
$V_{GS}$	Gate-source Voltage	±	20	V
$I_D$	Drain Current (continuous) at T <sub>c</sub> = 25 °C	16	11	Α
$I_D$	Drain Current (continuous) at T <sub>c</sub> = 100 °C	10	7	Α
I <sub>DM</sub> (•)	Drain Current (pulsed)	64	64	Α
$P_{tot}$	Total Dissipation at T <sub>c</sub> = 25 °C	60	30	W
	Derating Factor	0.4	0.2	W/°C
V <sub>ISO</sub>	Insulation Withstand Voltage (DC)	_	2000	V
dV/dt	Peak Diode Recovery voltage slope	6		V/ns
T <sub>stg</sub>	Storage Temperature	-65 to 175		°C
Tj	Max. Operating Junction Temperature	1	75	°C

<sup>(•)</sup> Pulse width limited by safe operating area

New RDS (on) spec. starting from JULY 98

(1)  $I_{SD} \le 16$  A,  $di/dt \le 200$  A/ $\mu$ s,  $V_{DD} \le V_{(BR)DSS}$ ,  $T_j \le T_{JMAX}$ 

June 1998

### STP16NE06/FP

### THERMAL DATA

			TO-220	TO-220FP	
R <sub>thj-case</sub>	Thermal Resistance Junction-case	Max	2.5	5	°C/W
R <sub>thj-amb</sub> R <sub>thc-sink</sub> T <sub>I</sub>	Thermal Resistance Junction-ambient Thermal Resistance Case-sink Maximum Lead Temperature For Soldering F	Max Typ Purpose	62 0. 30	5	°C/W °C/W °C

### **AVALANCHE CHARACTERISTICS**

Symbol	Parameter	Max Value	Unit
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T <sub>j</sub> max)	16	А
E <sub>AS</sub>	Single Pulse Avalanche Energy (starting $T_i = 25$ °C, $I_D = I_{AR}$ , $V_{DD} = 25$ V)	80	mJ

# **ELECTRICAL CHARACTERISTICS** ( $T_{case} = 25$ $^{\circ}C$ unless otherwise specified) OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source Breakdown Voltage	$I_D = 250 \ \mu A$ $V_{GS} = 0$	60			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	$V_{DS} = Max Rating$ $V_{DS} = Max Rating$ $^{\circ}C$ $T_{c} = 125$			1 10	μΑ μΑ
I <sub>GSS</sub>	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 20 V			± 100	nA

### ON (\*)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}$ $I_D = 250 \mu A$	2	3	4	٧
R <sub>DS(on)</sub>	Static Drain-source On Resistance	$V_{GS} = 10V  I_D = 8 A$		0.080	0.100	Ω
I <sub>D(on)</sub>	On State Drain Current	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $V_{GS} = 10 \text{ V}$	16			А

### **DYNAMIC**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
gfs (*)	Forward Transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$ $I_{D} = 8 \text{ A}$		6		Ø
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V <sub>DS</sub> = 25 V f = 1 MHz V <sub>GS</sub> = 0		760 100 30	1000 140 45	pF pF pF

### **ELECTRICAL CHARACTERISTICS** (continued)

### **SWITCHING ON**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub> t <sub>r</sub>	Turn-on Time Rise Time	$V_{DD} = 30 \text{ V}$ $I_{D} = 8 \text{ A}$ $R_{G} = 4.7 \text{ W}$ $V_{GS} = 10 \text{ V}$		10 35	80 40	ns ns
$egin{array}{c} Q_{g} \ Q_{gs} \ Q_{gd} \end{array}$	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 40 \text{ V}$ $I_{D} = 16 \text{ A}$ $V_{GS} = 10 \text{ V}$		20 5 7	30	nC nC nC

### www.DataSheet4USWITCHING OFF

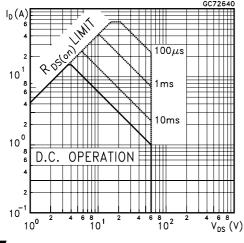
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
$t_{r(Voff)} $ $t_{f}$ $t_{c}$	Off-voltage Rise Time Fall Time Cross-over Time	$V_{DD} = 48 \text{ V}$ $I_{D} = 16 \text{ A}$ $R_{G} = 4.7 \Omega$ $V_{GS} = 10 \text{ V}$		7 18 30	10 25 45	ns ns ns

### SOURCE DRAIN DIODE

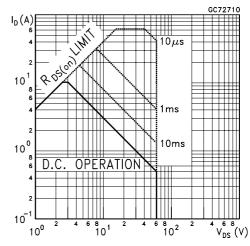
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub> I <sub>SDM</sub> (•)	Source-drain Current Source-drain Current (pulsed)				16 64	A A
V <sub>SD</sub> (*)	Forward On Voltage	I <sub>SD</sub> = 16 A V <sub>GS</sub> = 0			1.5	V
t <sub>rr</sub>	Reverse Recovery Time	$I_{SD} = 16 \text{ A}$		70		ns
$Q_{rr}$	Reverse Recovery	is a second		0.21		μС
$I_{RRM}$	Charge Reverse Recovery Current			6		Α

<sup>(\*)</sup> Pulsed: Pulse duration = 300 μs, duty cycle 1.5 %

### Safe Operating Area for TO-220



### Safe Operating Area for TO-220FP

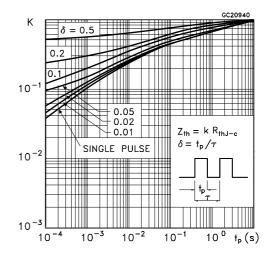


<sup>(•)</sup> Pulse width limited by safe operating area

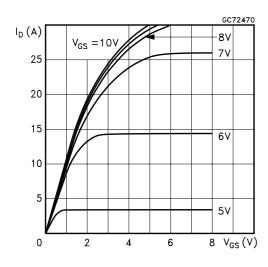
### Thermal Impedance for TO-220

# $\begin{array}{c} \text{K} \\ \delta = 0.5 \\ \hline \\ 0.2 \\ \hline \\ 0.02 \\ \hline \\ 0.05 \\ \hline \\ 0.02 \\ \hline \\ 0.05 \\ \hline \\ 0.001 \\$

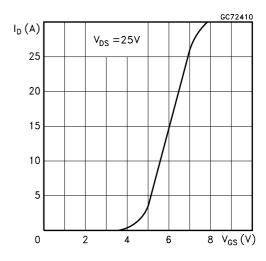
### Thermal Impedance for TO-220FP



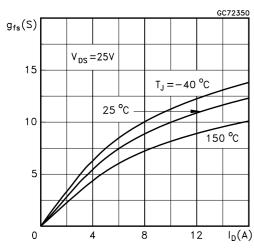
### **Output Characteristics**



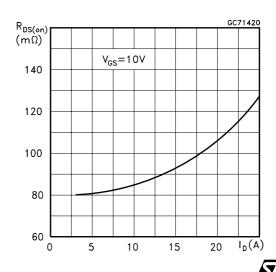
**Transfer Characteristics** 



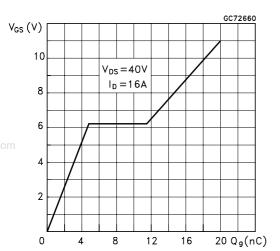
### Transconductance



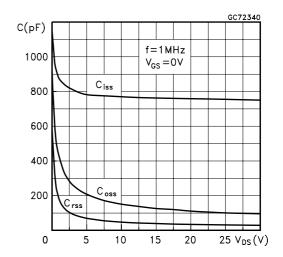
### Static Drain-source On Resistance



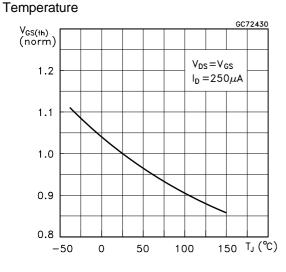
### Gate Charge vs Gate-source Voltage



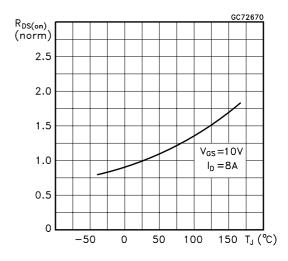
### Capacitance Variations



# Normalized Gate Threshold Voltage vs



Normalized On Resistance vs Temperature



### Source-drain Diode Forward Characteristics

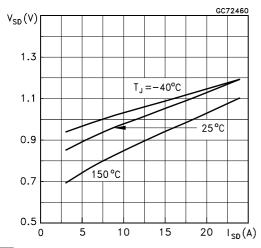
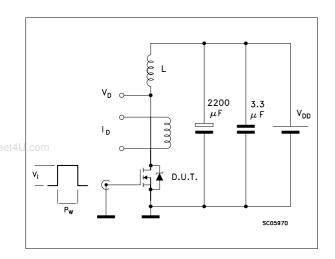
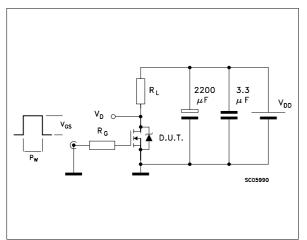


Fig. 1: Unclamped Inductive Load Test Circuit



**Fig. 3:** Switching Times Test Circuits For Resistive Load



**Fig. 5:** Test Circuit For Inductive Load Switching And Diode Recovery Times

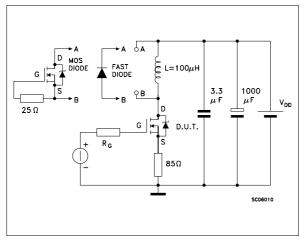


Fig. 2: Unclamped Inductive Waveform

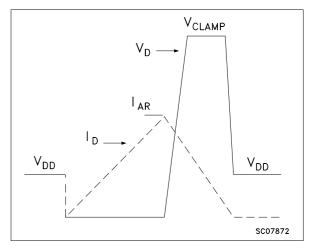
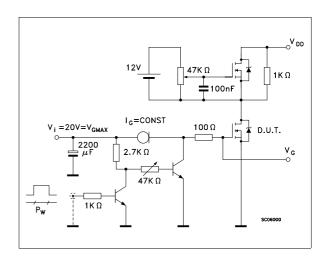


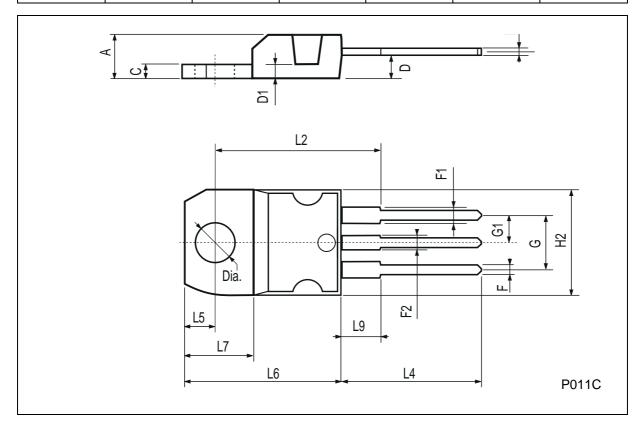
Fig. 4: Gate Charge test Circuit



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### **TO-220 MECHANICAL DATA**

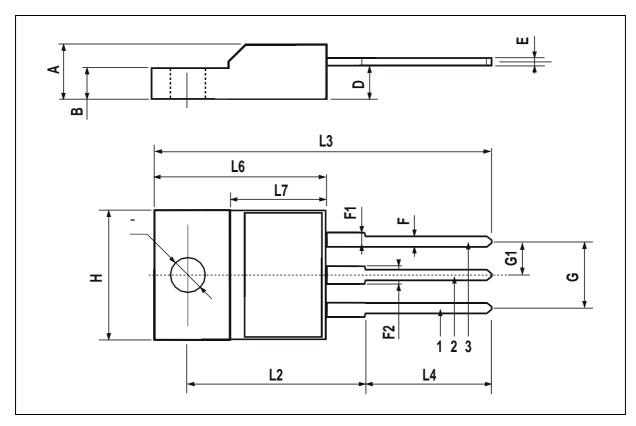
	DIM.		mm			inch	
	DIWI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
	А	4.40		4.60	0.173		0.181
	С	1.23		1.32	0.048		0.051
	D	2.40		2.72	0.094		0.107
www.DataSheet4U	D1		1.27			0.050	
www.DataSileet40	E	0.49		0.70	0.019		0.027
	F	0.61		0.88	0.024		0.034
	F1	1.14		1.70	0.044		0.067
	F2	1.14		1.70	0.044		0.067
	G	4.95		5.15	0.194		0.203
	G1	2.4		2.7	0.094		0.106
	H2	10.0		10.40	0.393		0.409
	L2		16.4			0.645	
	L4	13.0		14.0	0.511		0.551
	L5	2.65		2.95	0.104		0.116
	L6	15.25		15.75	0.600		0.620
	L7	6.2		6.6	0.244		0.260
	L9	3.5		3.93	0.137		0.154
	DIA.	3.75		3.85	0.147		0.151



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### **TO-220FP MECHANICAL DATA**

DIM.		mm			inch	
DIIVI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
А	4.4		4.6	0.173		0.181
В	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
.com E	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.7	0.045		0.067
F2	1.15		1.7	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
Н	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	0.385		0.417
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126



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